

## FEATURES

- \* Ideal for surface mount applications
- \* Easy pick and place
- \* Built-in strain relief
- \* Low forward voltage drop

## MECHANICAL DATA

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Terminals: Solder plated, solderable per MIL-STD-202F method 208 guaranteed
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any

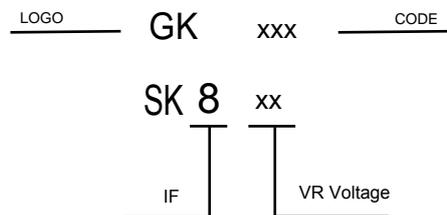


## VOLTAGE RANGE

150 to 200 Volts

## CURRENT

8.0 Ampere



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

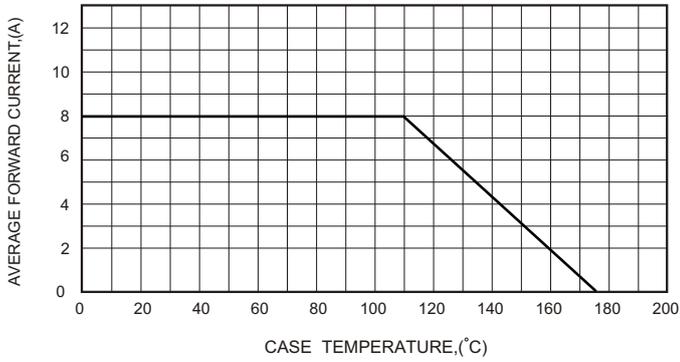
TYPE NUMBER	SK815	SK820	UNITS
Maximum Recurrent Peak Reverse Voltage	150	200	V
Maximum RMS Voltage	105	140	V
Maximum DC Blocking Voltage	150	200	V
Maximum Average Forward Rectified Current	8.0		A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150		A
Maximum Instantaneous Forward Voltage at 8.0A	0.92		V
Maximum DC Reverse Current $T_a=25^\circ\text{C}$	20		$\mu\text{A}$
at Rated DC Blocking Voltage $T_a=125^\circ\text{C}$	5		mA
Typical Junction Capacitance (Note1)	400		pF
Typical Thermal Resistance $R_{JL}$ (Note 2)	16		$^\circ\text{C}/\text{W}$
Operating Temperature Range $T_J$	-55 to +175		$^\circ\text{C}$
Storage Temperature Range $T_{STG}$	-55 to +175		$^\circ\text{C}$

### NOTES:

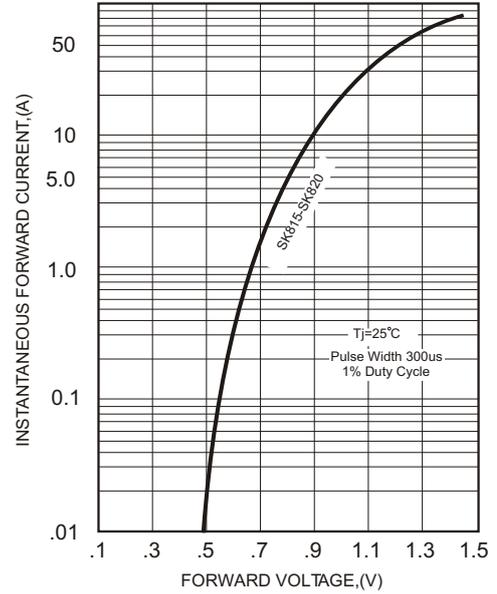
1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead.

**RATING AND CHARACTERISTIC CURVES**

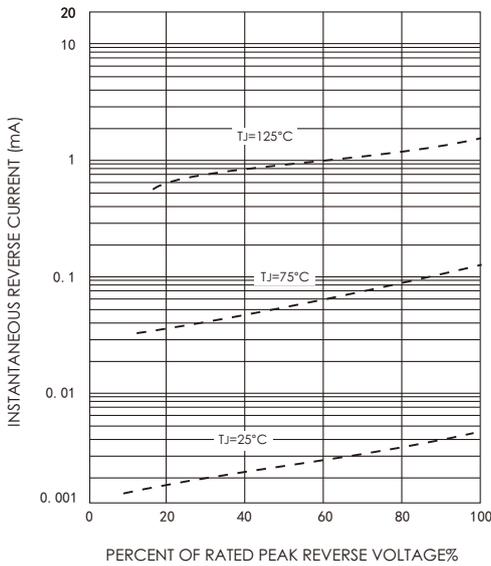
**FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE**



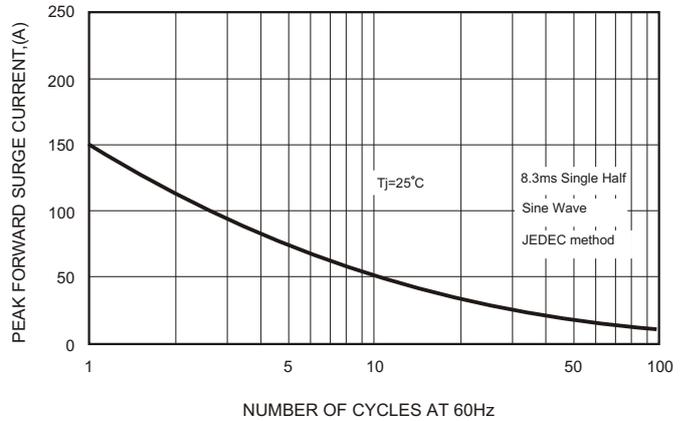
**FIG.2-TYPICAL FORWARD CHARACTERISTICS**



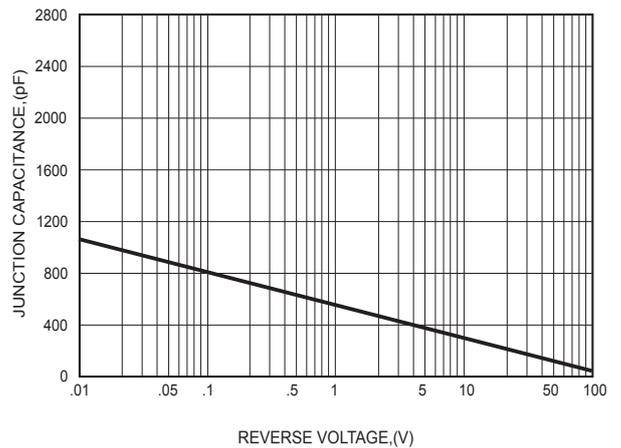
**FIG.3 - TYPICAL REVERSE CHARACTERISTICS**



**FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



**FIG.5-TYPICAL JUNCTION CAPACITANCE**



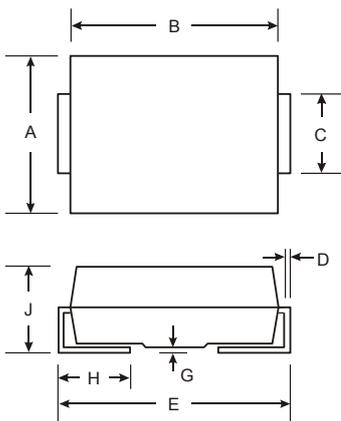
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C

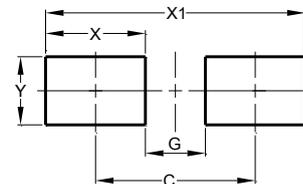


Package Dimensions & Suggested Pad Layout

SMB



SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.70
C	1.91	2.11
D	0.15	0.31
E	5.08	5.59
G		0.20
H	0.76	1.50
J	2.13	2.44
All Dimensions in mm		



Dimensions	Value (in mm)
C	4.70
G	2.20
X	2.50
X1	7.20
Y	2.80

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.60±0.20
		D1	1.60±0.20
		E	1.75±0.20
		F	5.50±0.15
		W	12.00±0.20
		A0	4.00±0.20
		B0	5.45±0.20
		K0	2.50±0.25
		T	0.20±0.10
		13" Reel	
		D3	73.0Min.
		D4	14.0±2.5
		W1	16.0±2.5
		Quantity: 3000PCS	